1. Remove part.

2. Dress site by wicking off residual solder with solder wick or de-soldering tool.

3. Clean site.

4. Remove release liner from back of StencilQuik™ stencil.

5. Align StencilQuik™ by positioning the diagonally opposite corner apertures over the corresponding pads. **NOTE:** Ensure that the pads are centered in the apertures.

6. Place the StencilQuik™ on the board applying pressure to the stencil to activate the adhesive. **NOTE:** Do not apply pressure until satisfied with alignment.

7. Tape off the area around the periphery of the part site with Kapton™ tape. **NOTE:** Ensure that the tape overlaps the outside edge of the StencilQuik™.

8. Squeegee solder paste across the top of the StencilQuik™ making sure all of the apertures are filled.

9. Remove the masking tape applied to the periphery of the reworked area applied in step #7.

10. Wipe off the excess solder paste from the top of the StencilQuik™ with a lint-free wipe.

11. Gently place the properly conditioned part aligning the balls or leads of the part with the filled apertures.

12. Reflow the part.

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**BEST**

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